

## Lecture 15 - p-n Junction (*cont.*)

March 9, 2007

### Contents:

1. Ideal p-n junction out of equilibrium (cont.)
2. pn junction diode: parasitics, dynamics

### Reading assignment:

del Alamo, Ch. 6, §6.2 (6.2.4), §6.3

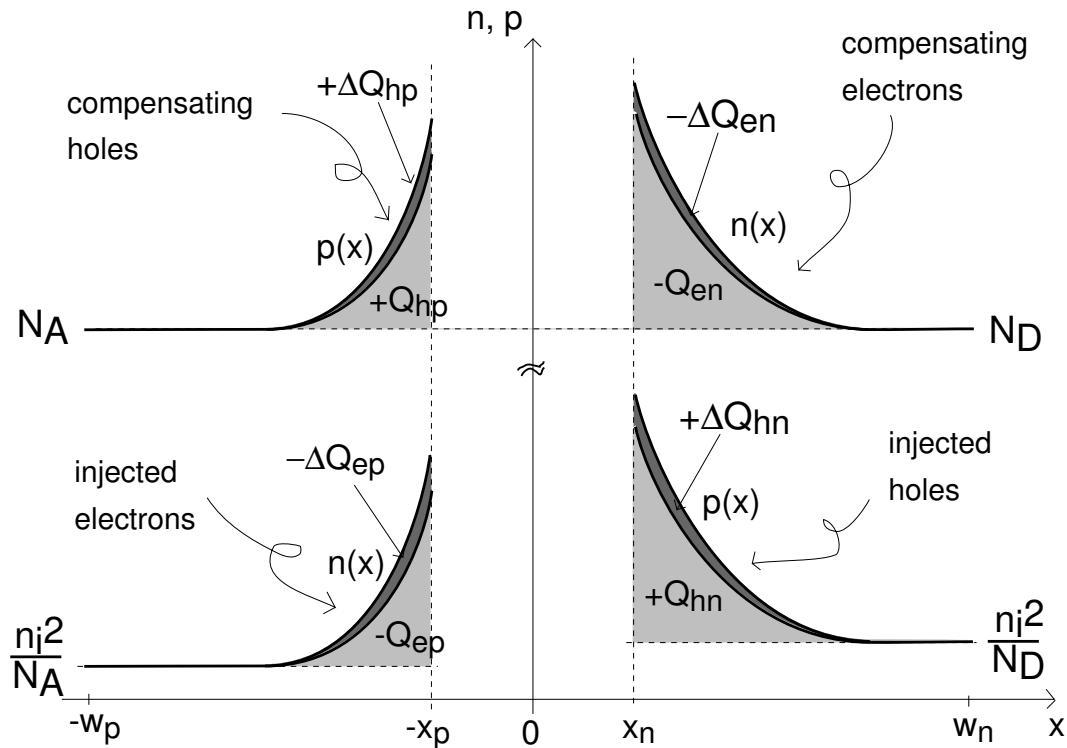
## Key questions

- What happens to the *majority carriers* in a pn junction under bias?
- What are the main practical issues in synthesizing pn junction diodes?
- How does a pn junction switch? What dominates its dynamic behavior?

## 1. Ideal p-n junction out of equilibrium (cont.)

### □ Minority carrier storage

Quasi-neutrality in QNR's demands  $n' \simeq p'$ . Consequences:



In n-QNR, quasi-neutrality implies:

$$Q_{hn} \simeq |Q_{en}| \equiv Q_n$$

Also, if  $V \uparrow \rightarrow Q_{hn} \uparrow \rightarrow |Q_{en}| \uparrow$  with:

$$\Delta Q_{hn} \simeq |\Delta Q_{en}| \equiv \Delta Q_n$$

$\Delta Q_{hn}$  supplied from p-contact,  $\Delta Q_{en}$  supplied from n-contact.

Looks like a capacitor  $\Rightarrow$  **diffusion capacitance**.

Diffusion capacitance (per unit area):

$$C_d = \frac{dQ_n}{dV} + \frac{dQ_p}{dV}$$

with:

$$Q_n = q \int_{x_n}^{w_n} p'(x) dx$$

$$Q_p = q \int_{-w_p}^{-x_p} n'(x) dx$$

- If both sides are "long":

$$Q_n = q L_h p'(x_n) = \tau_h J_h(x_n)$$

$$Q_p = q L_e n'(-x_p) = \tau_e J_e(-x_p)$$

and

$$C_d \simeq \frac{q}{kT} [\tau_h J_h(x_n) + \tau_e J_e(-x_p)] = \frac{q}{kT} (\tau_h J_{hs} + \tau_e J_{es}) \exp \frac{qV}{kT}$$

- If both sides are short and  $S = \infty$ :

$$\begin{aligned} Q_n &= q \frac{1}{2} p'(x_n)(w_n - x_n) = \tau_{tn} J_h(x_n) \\ Q_p &= q \frac{1}{2} n'(-x_p)(w_p - x_p) = \tau_{tp} J_e(-x_p) \end{aligned}$$

with  $\tau_{tn}$  and  $\tau_{tp}$  are the minority carrier transit times through QNR's:

$$\begin{aligned} \tau_{tn} &= \frac{(w_n - x_n)^2}{2D_h} \\ \tau_{tp} &= \frac{(w_p - x_p)^2}{2D_e} \end{aligned}$$

Then:

$$C_d \simeq \frac{q}{kT} [\tau_{tn} J_h(x_n) + \tau_{tp} J_e(-x_p)] = \frac{q}{kT} (\tau_{tn} J_{hs} + \tau_{tp} J_{es}) \exp \frac{qV}{kT}$$

Similar result to long diode!

- General expression:

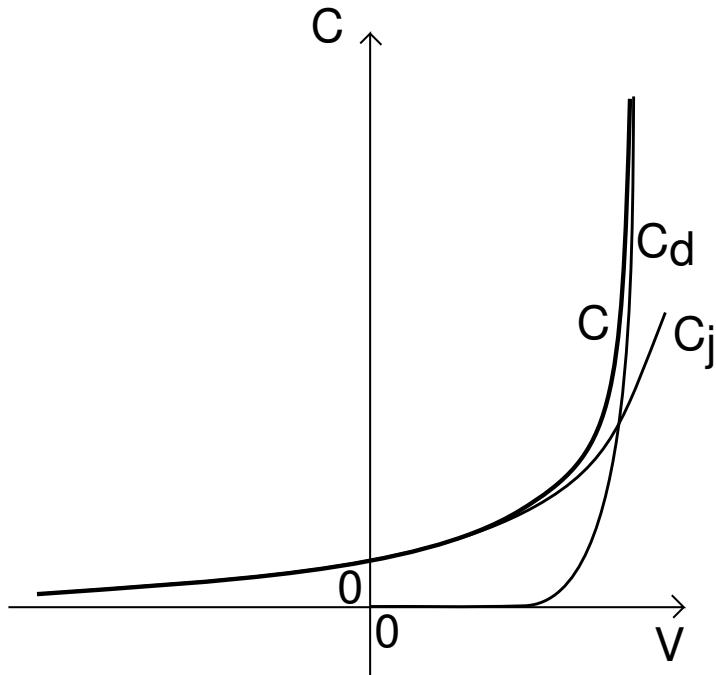
$$C_d = \frac{q}{kT} \sum_{n,p} \text{dominant minority carrier time constant} \\ \times \text{injected minority carrier current density}$$

$C_d$  grows exponentially in forward bias, negligible in reverse bias:

$$C_d \sim \exp \frac{qV}{kT}$$

[check that  $C_d \sim \exp \frac{qV}{kT}$  and not  $\sim \exp \frac{qV}{kT} - 1$ ]

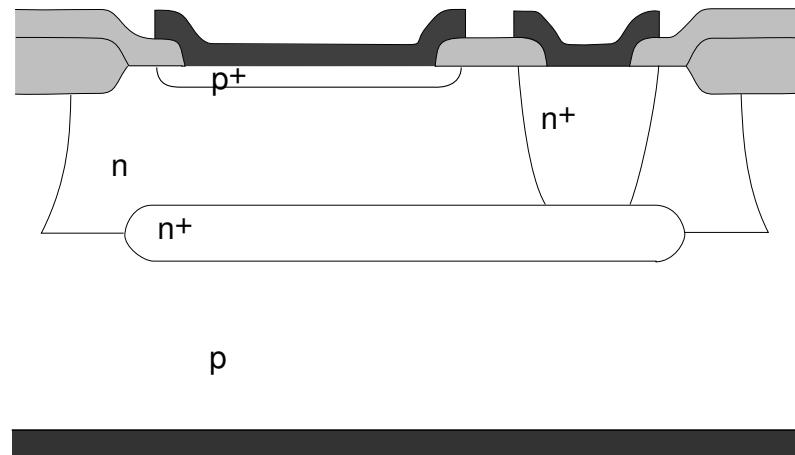
- Total diode capacitance:



## 2. p-n junction diode

- pn junctions present in most semiconductor devices (BJTs and MOSFETs).
- pn junction diodes used in rectifying circuits, detectors in communications applications, bias shifters, input protection devices against electrostatic discharge.
- For integrated p-n diodes, no special process steps available.

Typical cross section of p-n diode implemented in BJT process:

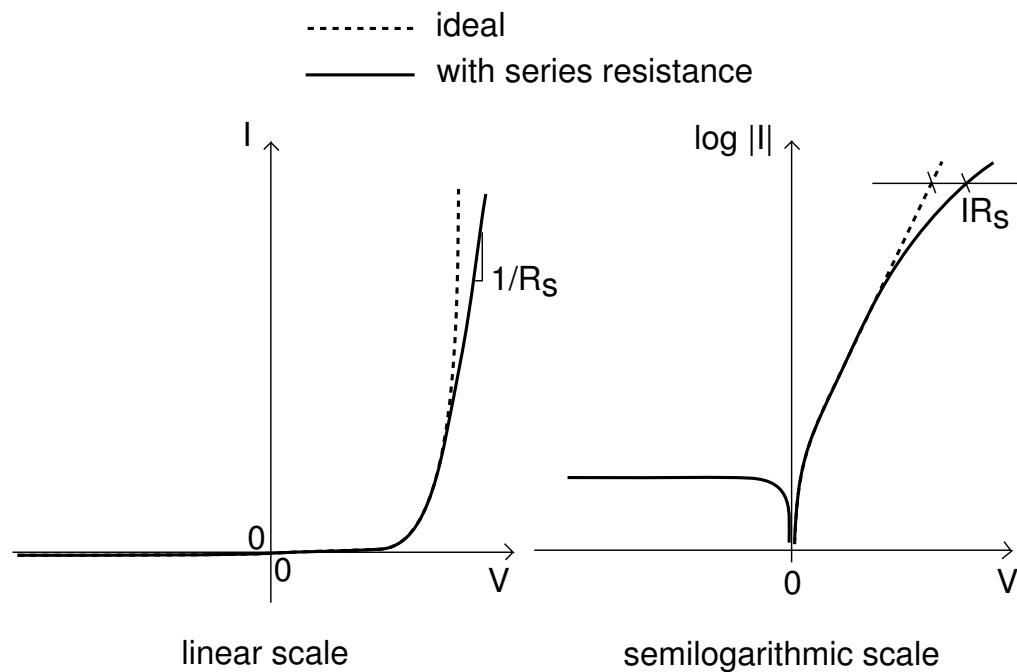


## □ Parasitics

### ★ Series resistance:

- Accounts for ohmic drop in QNR's (neglected so far).
- Reduces internal diode voltage  $\rightarrow I \downarrow$

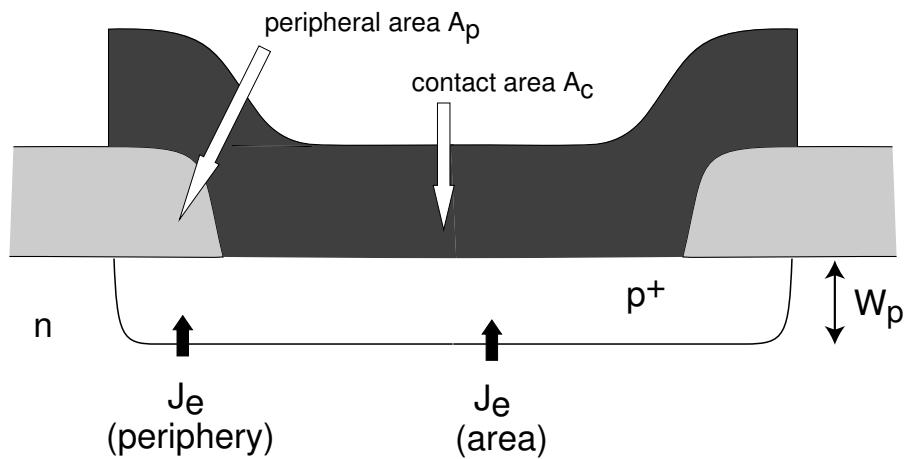
$$I = I_s \left[ \exp \frac{q(V - IR_s)}{kT} - 1 \right]$$



- Higher  $V_F$  required to deliver desired  $I_F \rightarrow$  more power dissipation, potential process control problems
- $RC$  time constant degraded.

★ *Minority carrier boundary conditions:*

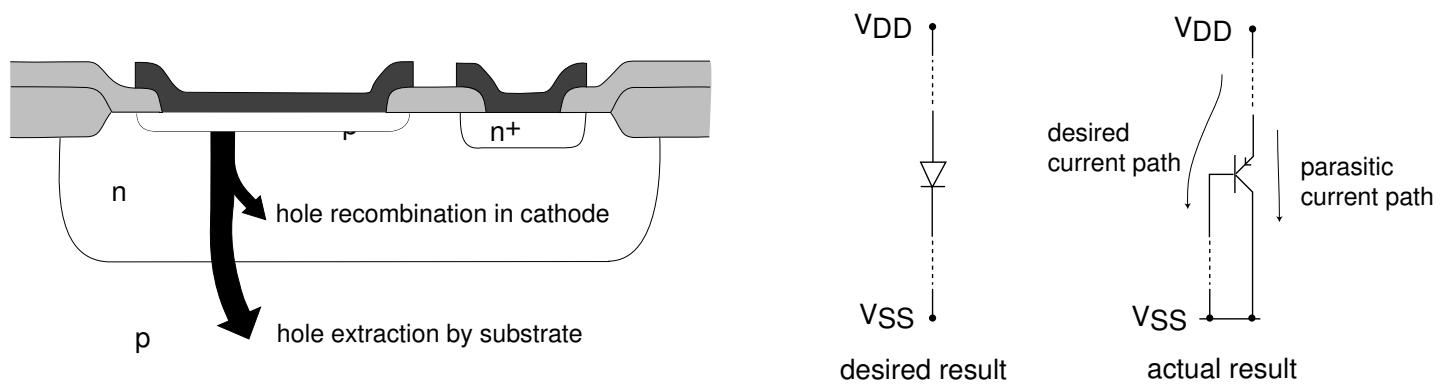
- At top surface: depending on relative depth of emitter, effective diode area changes
  - top surface=ohmic contact area ( $A_c, S = \infty$ )
  - + peripheral  $\text{SiO}_2$ -covered area ( $A_p, S = 0$ )



- if  $W_p \gg L_e$ , volume recombination only  $\rightarrow A_{eff} \simeq A_c + A_p$
- if  $W_p \ll L_e$ , surface recombination only  $\rightarrow A_{eff} \simeq A_c$
- At bottom surface: high-low junction, characterized by  $S_{hl}$ .

★ *Isolation:*

- Parasitic substrate p-n junction → needs to be reverse biased to avoid turning it on.
- Even reverse biased, substrate contributes parasitic capacitance.
- Additional danger: "bipolar effect" between diode and substrate → minority carriers can be extracted by substrate → current diverted away from main body of diode.

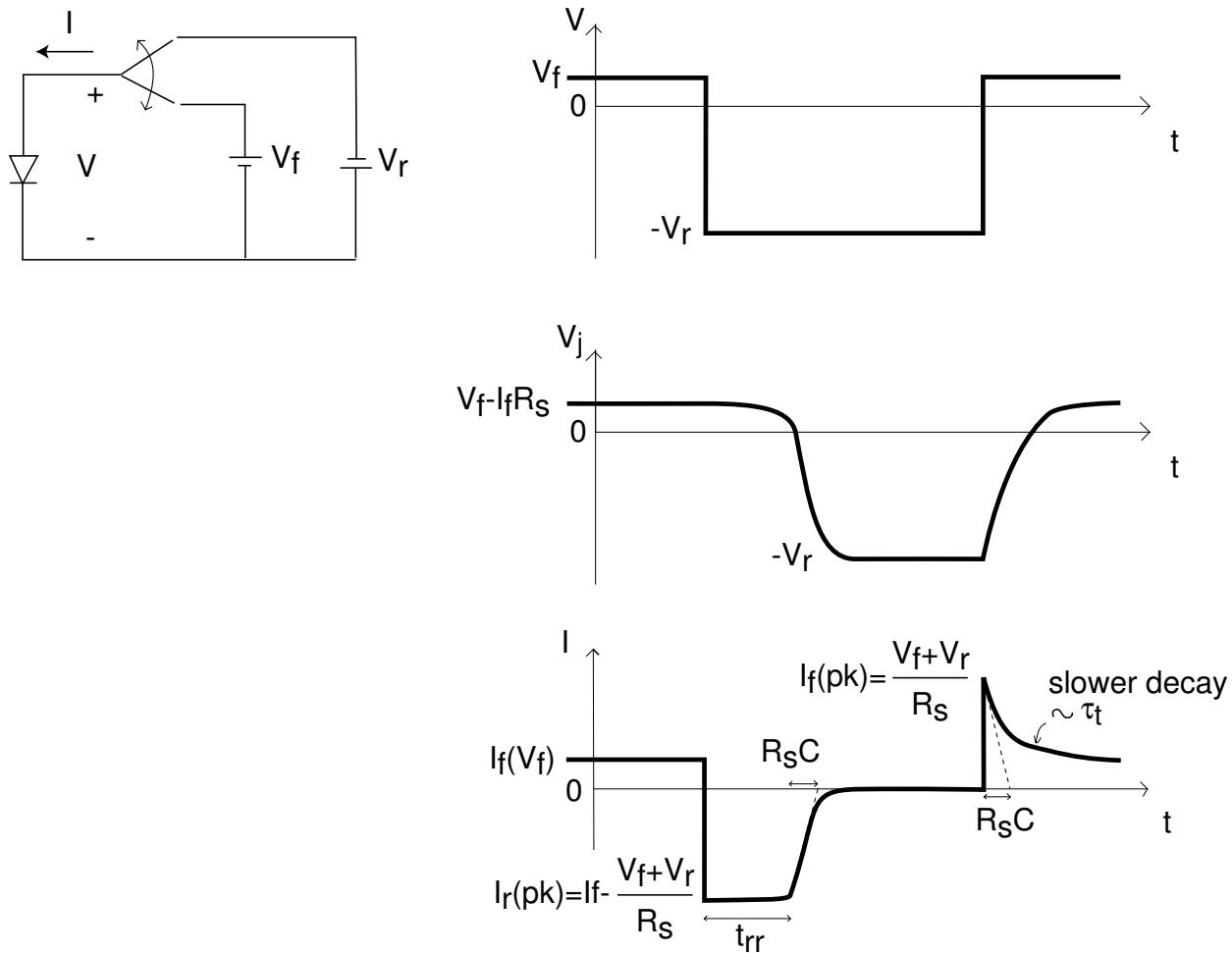


- Hard to make integrated pn diodes in CMOS process (unless they hang directly from the power rail that is connected to the substrate).
- Easier in bipolar since n<sup>+</sup> buried layer and collector plug can prevent minority carrier injection.

## □ Dynamics

Fundamental difference between p-n and Schottky diodes: minority carrier storage slows down p-n diode.

Consider simple voltage switching:

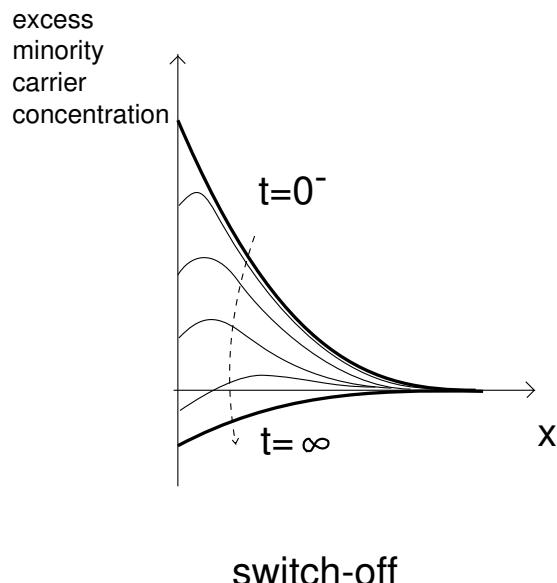


As in Schottky diode, delays associated with  $R_s C_j$ .

Additionally, delays associated with minority carrier storage.

★ Switch-off transient

Evolution of excess minority carrier concentration (long diode):

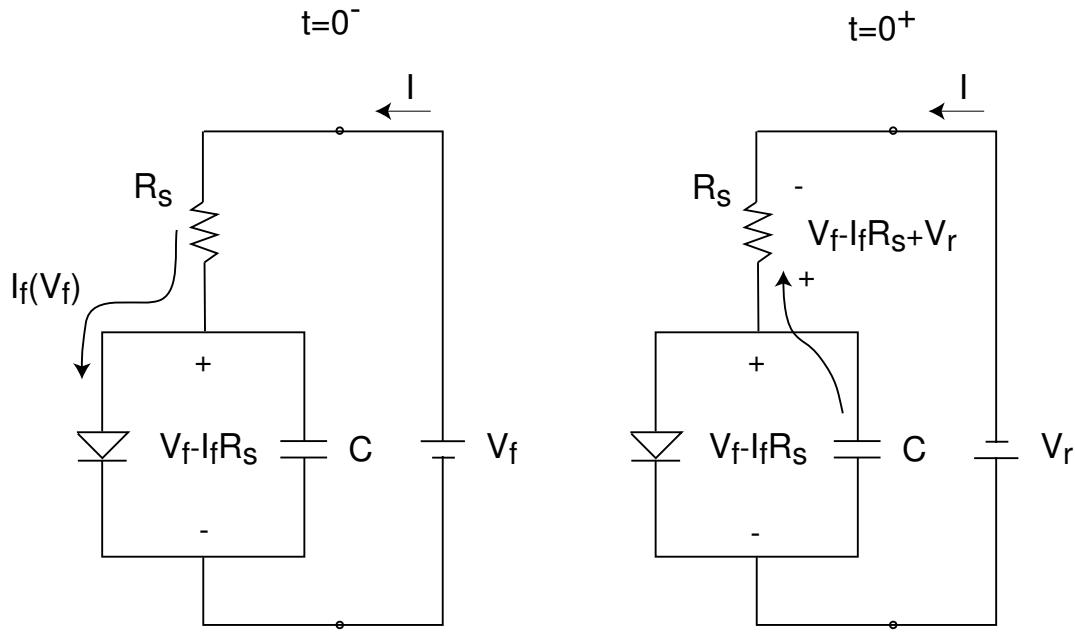


At  $t = 0^-$ ,  $V_f \rightarrow I_f$ ; minority carrier stored charge:

$$Q = \tau_t I_f$$

with  $\tau_t$ , dominant minority carrier time constant.

At  $t = 0^+$ , external  $V$  abruptly changes from  $V_f$  to  $V_r$ ; internal  $V$  cannot change abruptly → need to get rid of minority carriers!



$$I(0^-) = I_f(V_f) \quad I(0^+) = -\frac{1}{R_s}(V_f - I_f R_s + V_r) \simeq -\frac{V_r}{R_s}$$

Two phases to discharge:

**Phase I** - From  $V_j = V_f - I_f R_s$  to  $V_j \simeq 0$ .

Since  $Q \sim \exp \frac{qV_f}{kT}$ , as  $Q$  discharges,  $V_f$  cannot change much.

Discharge proceeds nearly at constant current  $I_r(pk) \simeq -\frac{V_r}{R_s}$

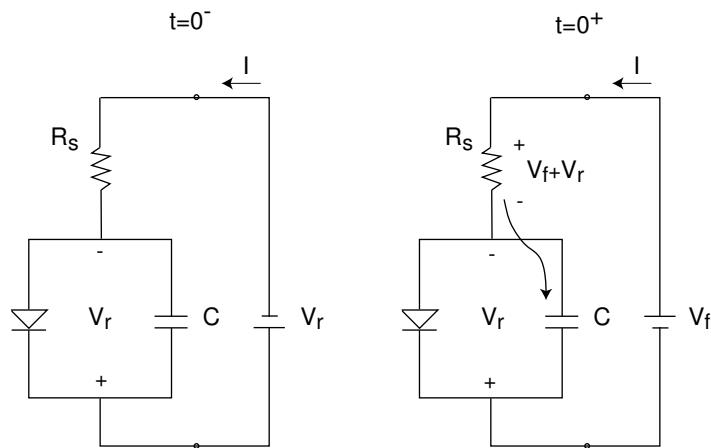
Time to discharge (*reverse recovery time*):

$$t_{rr} \simeq \frac{Q}{|I_r(pk)|} \simeq \tau_t \frac{I_f(V_f) R_s}{V_r}$$

**Phase II** - From  $V_j \simeq 0$  to  $V_j = -V_r$ .

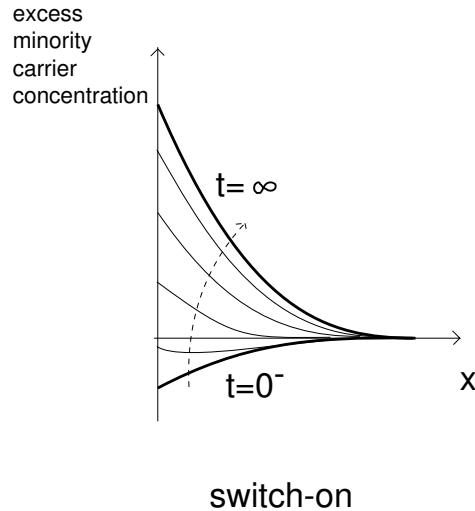
Charge depletion capacitance  $\rightarrow R_s C_j$  time constant (as in Schotky diode).

★ Switch-on transient



$$I(0^-) = -I_s \quad I(0^+) = \frac{V_f + V_r}{R_s}$$

Evolution of excess minority carrier concentration (long diode):

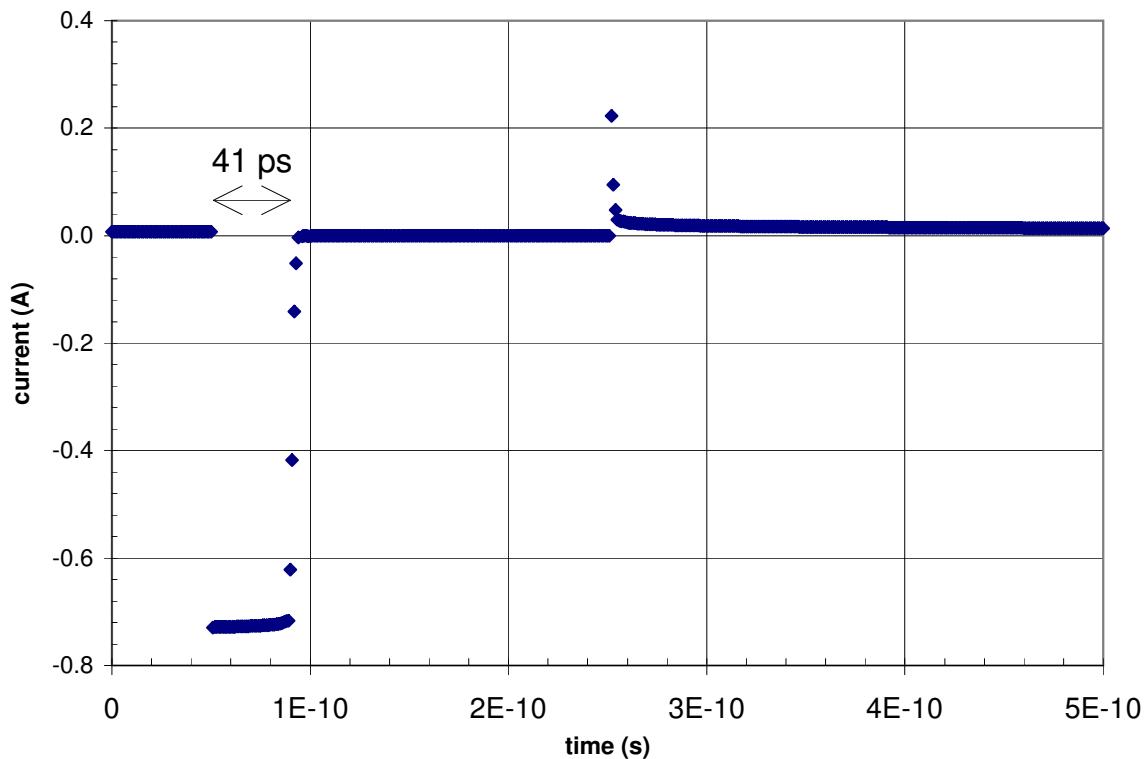


- First,  $R_s C_j$ -type charge up of junction capacitance.
- Then, minority carrier charge injection  $\rightarrow$  takes  $\tau_t$ .

Example of SPICE simulations:

$\mathbf{IS} = 6e-17$ ,  $\mathbf{N} = 1$ ,  $\mathbf{EG} = 1.12$ ,  $\mathbf{RS} = 8$ ,  $\mathbf{CJO} = 1.2e-13$ ,  $\mathbf{VJ} = 0.6$ ,  
 $\mathbf{M} = 0.41$ ,  $\mathbf{XTI} = 3.814$ , and  $\mathbf{TT} = 4e - 9$

$$V_f = +0.89 \text{ V}, V_r = -5 \text{ V}$$



parameter	SPICE	hand calculation
$t_{rr}$	41 ps	46 ps
$\tau_{on}$	2.6 ns	4 ns
$I_{rr}$	730 mA	736 mA
$I_f(pk)$	?	736 mA

## Key conclusions

- *Diffusion capacitance* arises from minority carrier storage in QNR's and quasi-neutrality:

$$C_d = \frac{q}{kT} \Sigma_{n,p} (\text{dominant minority carrier time constant} \\ \times \text{minority carrier current density})$$

- $C_d \propto J \propto \exp \frac{qV}{kT} \Rightarrow C_d$  dominates in forward bias,  $C_j$  dominates in reverse bias.
- Difficult to implement integrated diodes in CMOS process: parasitic bipolar transistor.
- Dynamics of p-n diode dominated by minority carrier storage.
- *Reverse recovery time* is time required to eliminate minority carrier stored charge in switch-off transient.

## Self study

- Diffusion capacitance in short diode.
- Equivalent circuit models for pn diode